



# Voidless Hermetically Sealed Unidirectional Transient Voltage Suppressors

Qualified per MIL-PRF-19500/434

Qualified Levels: JAN, JANTX, and JANTXV

## **DESCRIPTION**

This series of industry recognized voidless hermetically sealed unidirectional Transient Voltage Suppressor (TVS) designs is military qualified and are ideal for high-reliability applications where a failure cannot be tolerated. They provide a Working Peak "Standoff" Voltage selection from 30.5 to 175 volts with 1500 watt ratings. They are very robust in hard-glass construction and also use an internal metallurgical bond identified as "Category 1" for high reliability applications. These devices are also available in a surface mount MELF package configuration as a special order. Microsemi also offers numerous other TVS products to meet higher and lower peak pulse power and voltage ratings in both through-hole and surface-mount packages.

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#### **FEATURES**

- High surge current and peak pulse power provides transient voltage protection for sensitive circuits.
- Triple-layer passivation.
- Internal "Category 1" metallurgical bonds.
- · Voidless hermetically sealed glass package.
- JAN, JANTX, and JANTXV military qualifications available per MIL-PRF-19500/434.
- Further options for screening in accordance with MIL-PRF-19500 for JANS equivalent level by using a "SP" prefix.
- RoHS compliant versions available (commercial grade only).

## **APPLICATIONS / BENEFITS**

- Military and other high reliability transient protection.
- Extremely robust construction.
- Working Peak "Standoff" Voltage (V<sub>WM</sub>) from 30.5 to 175 V.
- Available as 1500 watt Peak Pulse Power (PPP).
- ESD and EFT protection per IEC61000-4-2 and IEC61000-4-4 respectively.
- Secondary lightning protection per select levels in IEC61000-4-5.
- Flexible axial-leaded mounting terminals.
- Non-sensitive to ESD per MIL-STD-750 method 1020.
- Inherently radiation hard as described in Microsemi "MicroNote 050".

#### **MAXIMUM RATINGS** @ $T_A = 25$ °C unless otherwise noted.

Parameters/Test Conditions	Symbol	Value	Unit
Junction and Storage Temperature	$T_J$ and $T_{STG}$	-55 to +175	°C
Peak Pulse Power @ t <sub>p</sub> = 1.0 ms	P <sub>PP</sub>	1500	W
Rated Forward Surge Current @ t <sub>p</sub> = 8.33 ms	I <sub>FSM</sub>	150	A (pk)
Impulse repetition rate (duty factor)	I <sub>PP</sub>	0.01	%
Steady-State Power (Figure 4)	P <sub>D</sub>	3.0	W
Solder Temperature @ 10 s	T <sub>SP</sub>	260	°C

Notes: 1. Derate at 20 mW°C above T<sub>A</sub> = +25 °C. Steady-state power ratings with reference to ambient are for PC boards where thermal resistance from mounting point to ambient is sufficiently controlled where T<sub>J(MAX)</sub> is not exceeded.



"G" Package

# Also available by Special order:

**MELF Surface Mount** 

#### MSC - Lawrence

6 Lake Street, Lawrence, MA 01841 Tel: 1-800-446-1158 or (978) 620-2600 Fax: (978) 689-0803

#### MSC - Ireland

Gort Road Business Park, Ennis, Co. Clare, Ireland Tel: +353 (0) 65 6840044 Fax: +353 (0) 65 6822298

#### Website:

www.microsemi.com



#### **MECHANICAL and PACKAGING**

- CASE: Hermetically sealed voidless hard glass with tungsten slugs.
- TERMINATIONS: Axial-leads are tin/lead (Sn/Pb) over copper. RoHS compliant matte-tin available for commercial only.
- MARKING: Body painted and part number.
- POLARITY: Cathode band.
- Tape & Reel option: Standard per EIA-296. Consult factory for quantities.
- Weight: 1270 milligrams.
- See Package Dimensions on last page.

#### PART NOMENCLATURE JAN 1N5610 (e3)**Reliability Level RoHS Compliance** JAN = JAN Level e3 = RoHS compliant (available JANTX = JANTX Level on commercial grade only) JANTXV = JANTXV Level Blank = non-RoHS compliant SP = Reference JANS Blank = Commercial JEDEC type number See Electrical Characteristics table

SYMBOLS & DEFINITIONS				
Symbol	Definition			
I <sub>(BR)</sub>	Breakdown Current: The current used for measuring Breakdown Voltage V <sub>(BR)</sub> .			
$I_D$	Maximum Standoff Current: The maximum current that will flow at the specified voltage and temperature.			
I <sub>PP</sub>	Peak Pulse Current: The peak current during the impulse.			
$P_{PP}$	Peak Pulse Power: The peak power dissipation resulting from the peak impulse current I <sub>PP</sub> .			
T <sub>SP</sub>	Temperature Solder Pad: The maximum solder temperature that can be safely applied to the terminal.			
α <sub>V(BR)</sub>	Temperature Coefficient of Minimum Breakdown Voltage: The minimum voltage the device will exhibit at a specified current temperature.			
V <sub>(BR)</sub>	Minimum Breakdown Voltage: The minimum voltage the device will exhibit at a specified current.			
V <sub>C</sub>	Maximum clamping voltage at specified I <sub>PP</sub> (Peak Pulse Current) at the specified pulse conditions.			
$V_{WM}$	Working Peak Voltage: The maximum peak voltage that can be applied over the operating temperature range. This is also referred to as Standoff Voltage.			

#### **ELECTRICAL CHARACTERISTICS**

TYPE	MINIMUM BREAK DOWN VOLTAGE	BREAKDOWN CURRENT MAXIMUM dc CURRENT	WORKING PEAK REVERSE VOLTAGE	MAX STANDOFF CURRENT I <sub>D</sub>	MAXIMUM CLAMPING VOLTAGE V <sub>C</sub>	MAXIMUM PEAK PULSE CURRENT IPP		MAXIMUM TEMP. COEF. OF V <sub>(BR)</sub>
	V <sub>(BR)</sub> @ 1.0 mA	T <sub>A</sub> = +25 °C I <sub>(BR)</sub>	V <sub>WM</sub>	@ V <sub>wm</sub>	@ 10/1000 μs	@8/20 µs	@10/1000 μs	α <sub>V(BR)</sub>
	Volts	mA	V (pk)	μΑ	V (pk)	A (pk)	A (pk)	%/°C
1N5610	33.0	75.0	30.5	5	47.6	193	32.0	.093
1N5611	43.7	53.0	40.3	5	63.5	136	24.0	.094
1N5612	54.0	43.0	49.0	5	78.5	116	19.0	.096
1N5613	191	12.5	175	5	265	33	5.7	.100



#### **GRAPHS**

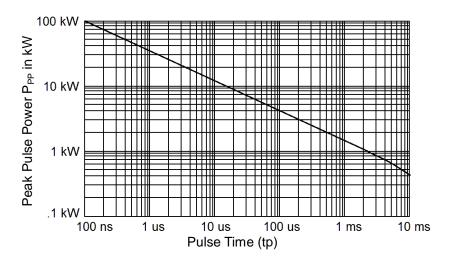


FIG. 1 – Non-repetitive peak pulse power rating curve NOTE: Peak power defined as peak voltage times peak current.

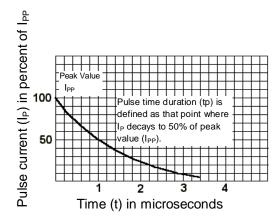


FIG. 2 Pulse wave form for exponential surge for 10/1000 µs

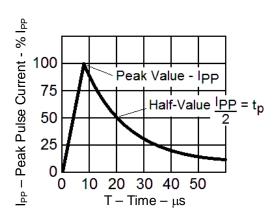


FIGURE 3 8/20  $\mu s$  CURRENT IMPULSE WAVEFORM TEST WAVEFORM PARAMETERS:  $t_r = 8 \mu sec$   $t_p = 20 \mu sec$ 

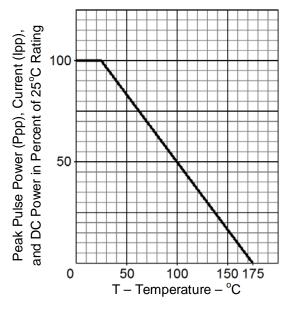
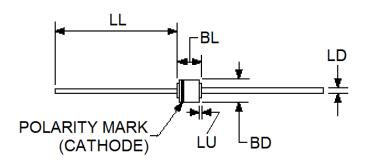


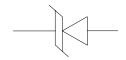
FIGURE 4
DERATING CURVE



## **PACKAGE DIMENSIONS**



Ltr	Inches		Millimeters		Notes
	Min	Max	Min	Max	
BD	.150	.185	3.81	4.70	3
BL	.160	.375	4.06	9.53	3
LD	.037	.042	0.94	1.07	
LL	.900	1.300	22.86	33.02	
LU		.050		1.27	4



Schematic Symbol

#### NOTES:

- 1. Dimensions are in inches.
- 2. Millimeters are given for general information only.
- 3. Package contour optional within BD and length BL.
- 4. Within this zone lead diameter may vary to allow for lead finishes and irregularities other than heat slugs.
- 5. In accordance with ASME Y14.5M, diameters are equivalent to  $\Phi x$  symbology.

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 MXP5KE14CA
 M15KP58A
 MSMCJ85CAe3
 MXLP5KE40CA
 MXLP5KE110Ae3
 M15KP85CAe3
 MSMCJ36CAe3

 MXP5KE20A
 MSMCJ15CA
 MXLP5KE8.5A
 MXP5KE5.0Ae3
 MXP5KE11A
 MXLP5KE9.0CA
 MXP5KE18CA

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 MXP5KE13CA
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 MXLP5KE58Ae3
 EPS24
 MXLP5KE54CA

 SM1624/TR13
 MSMCJ110CAe3
 MSMCJ15Ae3
 M15KP100A
 MXLP5KE58CA
 MXLSMBJSAC26
 MXP5KE120A

 MXLSMBJSAC22
 M15KP28Ae3
 MXLP5KE22CAe3
 MPT-18C
 MXLP5KE43CA
 MXLSMBJSAC26
 MXP5KE11Ae3

 MSMCJ78Ae3
 MXLP5KE54CAe3
 EPS28
 MSMCJ33Ae3
 MXLP5KE43CA
 MXLSMBJSAC50
 MXLP5KE5.0A

 MXLP5KE12A
 MXP5KE8.5CA
 MXP5KE90CA
 EPS24SM
 MXLP5KE100CA
 MSMCJ6.0Ae3
 MASMCJ18Ae3

 MXLP5KE14Ae3
 MXLP5KE64CA
 MXLP5KE10Ae3
 MSMCJ36Ae3
 MSMCJ36Ae3
 MXP5KE50Ae3
 MXP5KE50Ae3
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